## NCE01H21T

#### NCE N-Channel Enhancement Mode Power MOSFET

#### **Description**

The NCE01H21T uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of other applications.

#### **General Features**

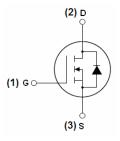
- $V_{DSS}$  =100V, $I_D$  =210A  $R_{DS(ON)} < 4.0 mΩ @ V_{GS}$ =10V (Typ: 3.1 mΩ)
- Good stability and uniformity with high E<sub>AS</sub>
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

#### **Application**

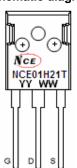
- DC motor drive
- High efficiency synchronous rectification in SMPS
- Uninterruptible power supply
- High speed power switching
- Hard switched and high frequency circuits

100% UIS TESTED!

100% ΔVds TESTED!



#### Schematic diagram



Marking and pin assignment



TO-247 top view

#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
NCE01H21T	NCE01H21T	TO-247	-	-	-

#### Absolute Maximum Ratings (T<sub>C</sub>=25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDSS	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous	I <sub>D</sub>	210	Α
Drain Current-Continuous(T <sub>C</sub> =100 °C)	I <sub>D</sub> (100℃)	140	Α
Pulsed Drain Current	I <sub>DM</sub>	850	Α
Maximum Power Dissipation	P <sub>D</sub>	385	W
Derating factor		2.57	W/℃
Single pulse avalanche energy (Note 3)	E <sub>AS</sub>	2300	mJ
Peak Diode Recovery dv/dt (Note 4)	dv/dt	13	V/ns



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# NCE01H21T

Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 175	$^{\circ}$
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#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Case (Note 1)	Rejc	0.39	°C/W
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### Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	100	110	-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =100V,V <sub>GS</sub> =0V	-	-	1	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V	-	-	±200	nA
On Characteristics						
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	2	3	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =40A	-	3.1	4.0	mΩ
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> =25V,I <sub>D</sub> =40A	300	-	-	S
Dynamic Characteristics	<u>.</u>					
Input Capacitance	C <sub>lss</sub>	\\ O5\\\\ O\\	-	16500	-	PF
Output Capacitance	C <sub>oss</sub>	V <sub>DS</sub> =25V,V <sub>GS</sub> =0V, F=1.0MHz	-	1061	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r=1.0lvlm2	-	811	-	PF
Switching Characteristics						
Turn-on Delay Time	t <sub>d(on)</sub>	V -20VI -2A	-	68	-	nS
Turn-on Rise Time	t <sub>r</sub>	V <sub>DD</sub> =30V,I <sub>D</sub> =2A	-	45	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{GEN}$ =2.5 $\Omega$ (Note2)	-	215	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	56	-	nS
Total Gate Charge	Qg	V -20VI -20A	-	377	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS}$ =30V, $I_{D}$ =30A, $V_{GS}$ =10V <sup>(Note2)</sup>	-	79	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	VGS-10V	-	118	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> =0V,I <sub>S</sub> =40A	-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	TJ = 25°C, IF = 75A	-	69	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note2)}$	-	108	-	nC
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

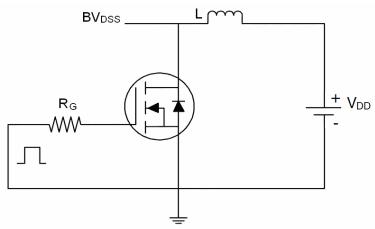
#### Notes:

- 1. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 2. Pulse Test: Pulse Width  $\leq$  400 $\mu$ s, Duty Cycle  $\leq$  2%.
- 3. EAS condition: Tj=25  $^{\circ}\text{C}$  ,V  $_{DD}$ =37.5V ,V  $_{G}$ =10V ,L=2mH ,Rg=25 $\Omega$  ,I  $_{AS}$ =37A
- 4. Isd $\leqslant$ 125A, di/dt $\leqslant$ 260A/ $\mu$ s, Vdd $\leqslant$ V(BR)dss, TJ  $\leqslant$ 175°C

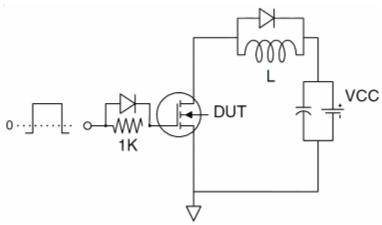


#### **Test circuit**

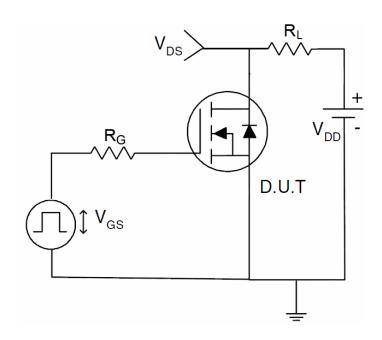
## 1) E<sub>AS</sub> test Circuits



### 2) Gate charge test Circuit:



#### 3) Switch Time Test Circuit:





#### **Typical Electrical and Thermal Characteristics**

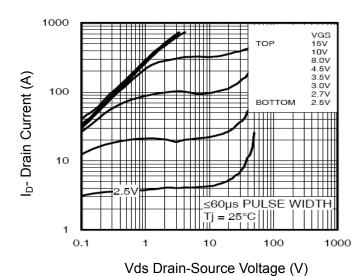
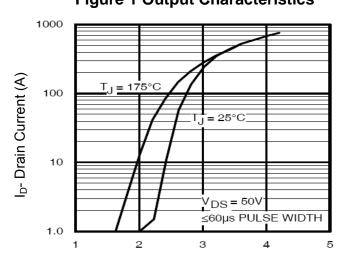


Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

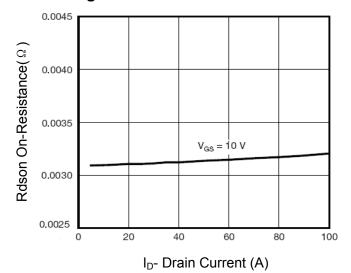
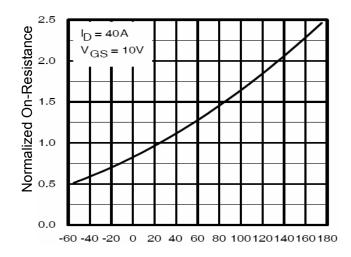


Figure 3 Rdson- Drain Current



T<sub>J</sub>-Junction Temperature(°C)

Figure 4 Rdson-JunctionTemperature

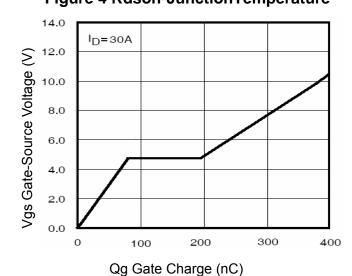


Figure 5 Gate Charge

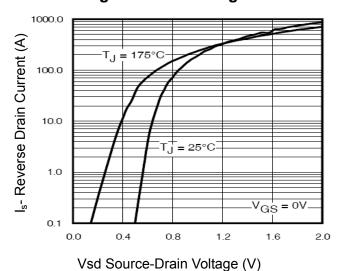
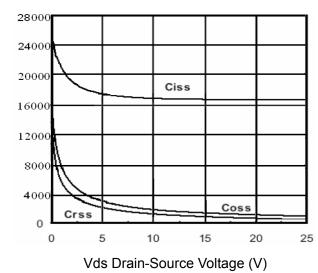


Figure 6 Source- Drain Diode Forward



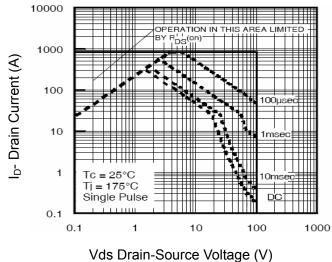
C Capacitance (pF)

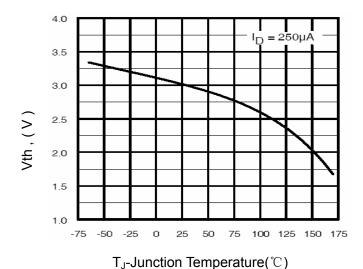


= 250µ/ 1.1 1.05 Normalized BVdss 0.95 0.9 0.85 -50 -25 25 50 75 100 125 150 175 T<sub>J</sub>-Junction Temperature(°C)

Figure 7 Capacitance vs Vds

Figure 9 BV<sub>DSS</sub> vs Junction Temperature





**Figure 8 Safe Operation Area** 

Figure 10 V<sub>GS(th)</sub> vs Junction Temperature

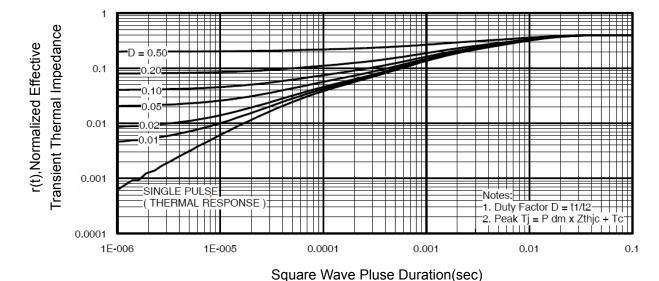


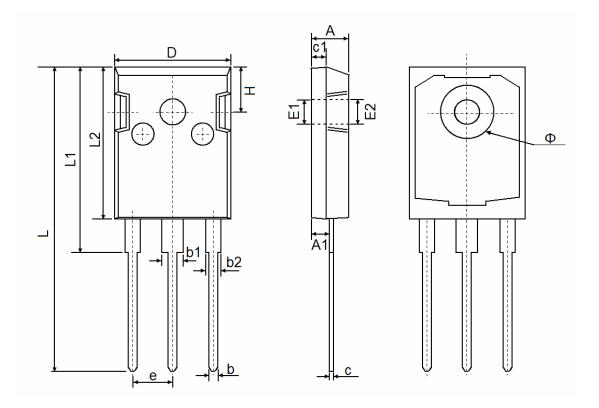
Figure 11 Normalized Maximum Transient Thermal Impedance

**Pb Free Product** 



# NCE01H21T

## **TO-247 Package Information**



Symbol	Dimensions	In Millimeters	Dimensions In Inches			
	Min.	Max.	Min.	Max.		
А	4.850	5.150	0.191	0.200		
A1	2.200	2.600	0.087	0.102		
b	1.000	1.400	0.039	0.055		
b1	2.800	3.200	0.110	0.126		
b2	1.800	2.200	0.071	0.087		
С	0.500	0.700	0.020	0.028		
c1	1.900	2.100	0.075	0.083		
D	15.450	15.750	0.608	0.620		
E1	3.50	0 REF	0.138 REF			
E2	3.60	3.600 REF		0.142 REF		
L	40.900	41.300	1.610	1.626		
L1	24.800	25.100	0.976	0.988		
L2	20.300	20.600	0.799	0.811		
Ф	7.100	7.300	0.280	0.287		
е	5.45	0 TYP	0.215 TYP			
Н	5.98	0 REF	0.235 REF			



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